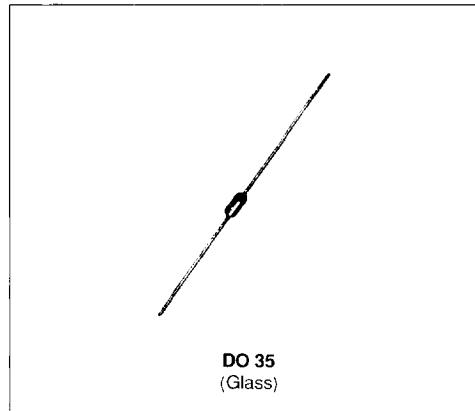


## SMALL SIGNAL SCHOTTKY DIODES


**DESCRIPTION**

General purpose metal to silicon diodes featuring very low turn-on voltage and fast switching.

These devices have integrated protection against excessive voltage such as electrostatic discharges.

**ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter		BAT 47	BAT 48	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage		20	40	V
$I_F$	Forward Continuous Current*	$T_a = 25^\circ C$		350	mA
$I_{FRM}$	Repetitive Peak Forward Current*	$t_p \leq 1s$ $\delta \leq 0.5$		1	A
$I_{FSM}$	Surge non Repetitive Forward Current*	$t_p = 10ms$		7.5	A
		$t_o = 1s$		1.5	
$P_{tot}$	Power Dissipation*	$T_a = 25^\circ C$		330	mW
$T_{S:J}$ $T_J$	Storage and Junction Temperature Range		– 65 to 150 – 65 to 125	°C °C	°C
$T_L$	Maximum Lead Temperature for Soldering during 10s at 4mm from Case			230	°C

**THERMAL RESISTANCE**

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction-ambient*	300	C/W

\* On infinite heatsink with 4mm lead length

**ELECTRICAL CHARACTERISTICS****STATIC CHARACTERISTICS**

<b>Symbol</b>	<b>Test Conditions</b>		<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
V <sub>(BR)</sub>	I <sub>R</sub> = 10µA	BAT 47	20			V
	I <sub>R</sub> = 25µA	BAT 48	40			
V <sub>F</sub> *	T <sub>J</sub> = 25°C I <sub>F</sub> = 0.1mA	All Types			0.25	V
	T <sub>J</sub> = 25°C I <sub>F</sub> = 1mA				0.3	
	T <sub>J</sub> = 25°C I <sub>F</sub> = 10mA				0.4	
	T <sub>J</sub> = 25°C I <sub>F</sub> = 30mA		BAT 47		0.5	
	T <sub>J</sub> = 25°C I <sub>F</sub> = 150mA				0.8	
	T <sub>J</sub> = 25°C I <sub>F</sub> = 300mA				1	
	T <sub>J</sub> = 25°C I <sub>F</sub> = 50mA		BAT 48		0.5	
	T <sub>J</sub> = 25°C I <sub>F</sub> = 200mA				0.75	
	T <sub>J</sub> = 25°C I <sub>F</sub> = 500mA				0.9	
I <sub>R</sub> *	T <sub>J</sub> = 25°C	V <sub>H</sub> = 1.5V	All Types		1	µA
	T <sub>J</sub> = 60°C				10	
	T <sub>J</sub> = 25°C	V <sub>H</sub> = 10V	BAT 47		4	
	T <sub>J</sub> = 60°C				20	
	T <sub>J</sub> = 25°C	V <sub>H</sub> = 20V			10	
	T <sub>J</sub> = 60°C				30	
	T <sub>J</sub> = 25°C	V <sub>H</sub> = 10V	BAT 48		2	
	T <sub>J</sub> = 60°C				15	
	T <sub>J</sub> = 25°C	V <sub>H</sub> = 20V			5	
	T <sub>J</sub> = 60°C				25	
	T <sub>J</sub> = 25°C	V <sub>H</sub> = 40V			25	
	T <sub>J</sub> = 60°C				50	

**DYNAMIC CHARACTERISTICS**

<b>Symbol</b>	<b>Test Conditions</b>		<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
C	T <sub>J</sub> = 25°C V <sub>R</sub> = 0V	f = 1MHz		20		pF
	T <sub>J</sub> = 25°C V <sub>R</sub> = 1V			12		
t <sub>rr</sub>	T <sub>J</sub> = 25°C I <sub>F</sub> = 10mA	V <sub>R</sub> = 1V	i <sub>rr</sub> = 1mA	R <sub>L</sub> = 100Ω	10	ns

\* Pulse test : t<sub>r</sub> ≤ 300µs δ < 2%.

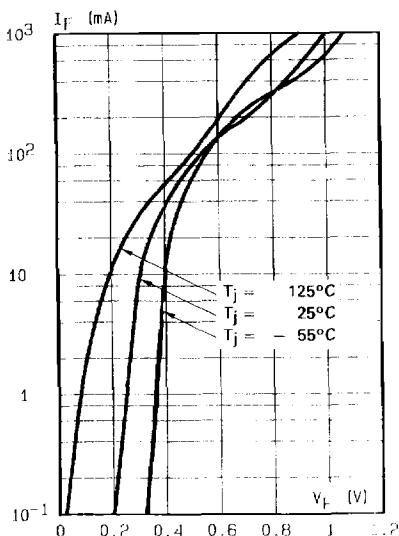


Fig.1 .. Forward current versus forward voltage at different temperatures (typical values).

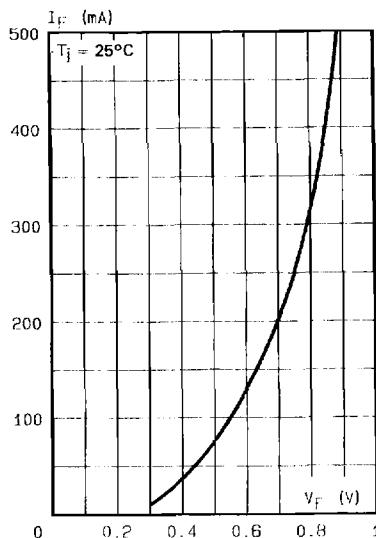


Fig.2 .. Forward current versus forward voltage (typical values).

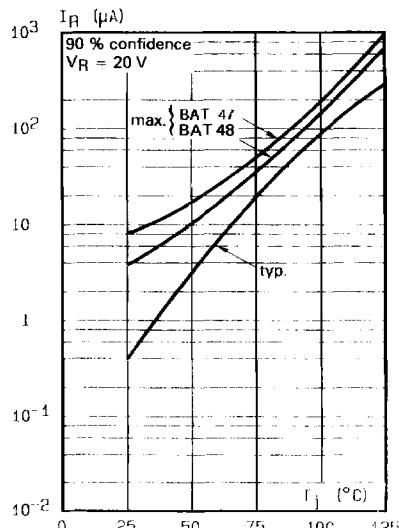


Fig.3 .. Reverse current versus junction temperature.

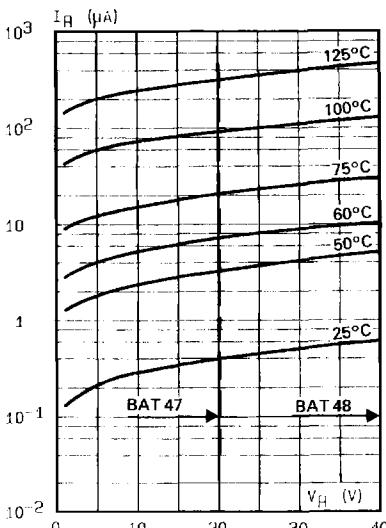


Fig.4 .. Reverse current versus continuous reverse voltage (typical values).

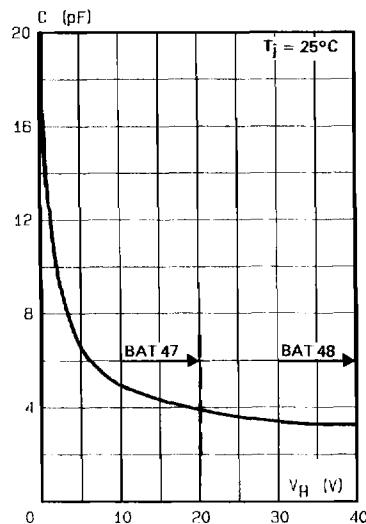
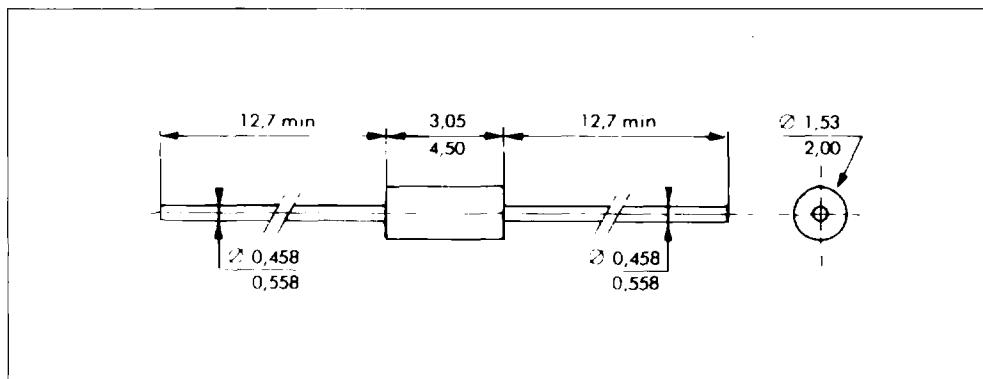


Fig.5 - Capacitance  $C$  versus  
reverse applied voltage  $V_R$   
(typical values).

#### PACKAGE MECHANICAL DATA

DO 35 Glass



Cooling method : by convection and conduction

Marking : clear, ring at cathode end.

Weight : 0.15g